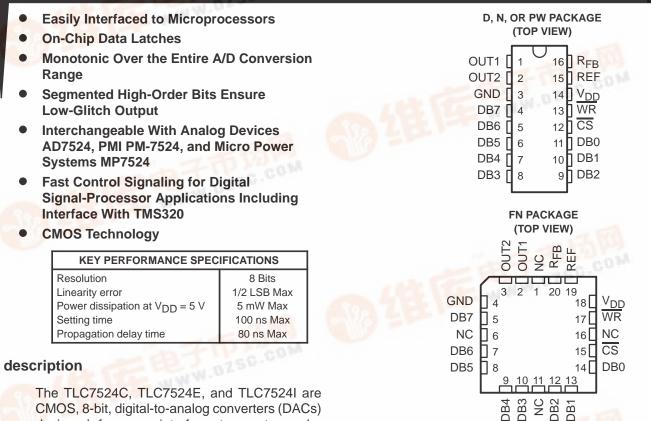
查询TLC7524CD供应商

捷多邦,专业PCFLCF7524C4小区07524E, TLC7524I 8-BIT MULTIPLYING DIGITAL-TO-ANALOG CONVERTERS

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NC-No internal connection



CMOS, 8-bit, digital-to-analog converters (DACs) designed for easy interface to most popular microprocessors.

The devices are 8-bit, multiplying DACs with input latches and load cycles similar to the write cycles of a random access memory. Segmenting the high-order bits minimizes glitches during changes in the most significant bits, which produce the highest glitch impulse. The devices provide accuracy to 1/2 LSB without the need for thin-film resistors or laser trimming, while dissipating less than 5 mW typically.

Featuring operation from a 5-V to 15-V single supply, these devices interface easily to most microprocessor buses or output ports. The 2- or 4-quadrant multiplying makes these devices an ideal choice for many microprocessor-controlled gain-setting and signal-control applications.

The TLC7524C is characterized for operation from 0°C to 70°C. The TLC7524I is characterized for operation from –25°C to 85°C. The TLC7524E is characterized for operation from –40°C to 85°C.

	AVAILABLE OPTIONS							
		PACKAGE	W -	M.M.				
TA	SMALL OUTLINE PLASTIC DIP (D)	PLASTIC CHIP CARRIER (FN)	PLASTIC DIP (N)	SMALL OUTLINE (PW)				
0°C to 70°C	TLC7524CD	TLC7524CFN	TLC7524CN	TLC7524CPW				
-25°C to 85°C	TLC7524ID	TLC7524IFN	TLC7524IN	TLC7524IPW				
-40°C to 85°C	TLC7524ED	TLC7524EFN	TLC7524EN	_				

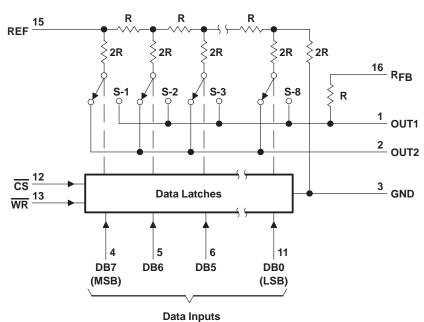


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functional block diagram



Terminal numbers shown are for the D or N package.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

upply voltage range, V _{DD}
igital input voltage range, V_{I}
eference voltage, V _{ref}
eak digital input current, I _I
perating free-air temperature range, T _A : TLC7524C
TLC7524I
TLC7524E
torage temperature range, T _{stg} –65°C to 150°C
ase temperature for 10 seconds, T _C : FN package
ead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D, N, or PW package



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recommended operating conditions

			′DD = 5 \	/	۷ı	OD = 15	V	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, VDD		4.75	5	5.25	14.5	15	15.5	V
Reference voltage, V _{ref}			±10			±10		V
High-level input voltage, V _{IH}		2.4			13.5			V
Low-level input voltage, VIL				0.8			1.5	V
CS setup time, t _{SU(CS)}		40			40			ns
CS hold time, th(CS)		0			0			ns
Data bus input setup time, t _{su(D)}		25			25			ns
Data bus input hold time, th(D)	Data bus input hold time, th(D)				10			ns
Pulse duration, WR low, tw(WR)		40			40			ns
	TLC7524C	0		70	0		70	
Operating free-air temperature, T _A	TLC7524I	-25		85	-25		85	°C
	TLC7524E	-40		85	-40		85	

electrical characteristics over recommended operating free-air temperature range, $V_{ref} = \pm 10$ V, OUT1 and OUT2 at GND (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V	DD = 5	V	V	_{DD} = 15	V	UNIT	
	FARAMETER		TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
IIН	High-level input curre	nt	$V_I = V_{DD}$			10			10	μΑ
١ _{IL}	Low-level input currer	nt	$V_{I} = 0$			-10			-10	μA
	Output leakage	OUT1	DB0–DB7 at 0 V, \overline{WR} , \overline{CS} at 0 V, $V_{ref} = \pm 10 V$			±400			±200	nA
likg	current	OUT2	DB0–DB7 at V _{DD} , \overline{WR} , \overline{CS} at 0 V, V _{ref} = ±10 V			±400			±200	ΠA
	Supply ourrept	Quiescent	DB0–DB7 at VIHmin or VILmax			1			2	mA
DD	Supply current	Standby	DB0–DB7 at 0 V or V _{DD}			500			500	μA
ksvs	Supply voltage sensiti ∆gain/∆V _{DD}	ivity,	$\Delta V_{DD} = \pm 10\%$		0.01	0.16		0.005	0.04	%FSR/%
Ci	Input capacitance, DB0–DB7, WR, CS		V _I = 0			5			5	pF
		OUT1				30			30	
		OUT2	DB0–DB7 at 0 V, \overline{WR} , \overline{CS} at 0 V			120			120	
Co	Output capacitance	OUT1				120			120	pF
		OUT2	DB0–DB7 at V _{DD} , WR, CS at 0 V			30			30	
	Reference input impe (REF to GND)	dance		5		20	5		20	kΩ



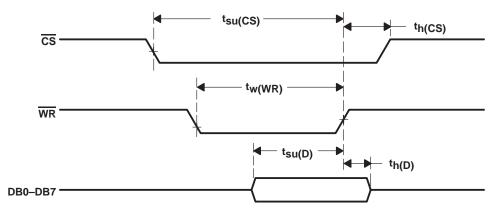
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operating characteristics over recommended operating free-air temperature range, $V_{ref} = \pm 10 V$, OUT1 and OUT2 at GND (unless otherwise noted)

DADAMETED	TEST CONDITIONS	V _{DD} = 5 V		V _{DD} = 15 V			UNIT	
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
Linearity error				±0.5			±0.5	LSB
Gain error	See Note 1			±2.5			±2.5	LSB
Settling time (to 1/2 LSB)	See Note 2			100			100	ns
Propagation delay from digital input to 90% of final analog output current	See Note 2			80			80	ns
Feedthrough at OUT1 or OUT2	$\frac{\text{Vref}}{\text{WR}} = \pm 10 \text{ V} (100\text{-kHz sinewave})$ WR and CS at 0 V, DB0–DB7 at 0 V			0.5			0.5	%FSR
Temperature coefficient of gain	$T_A = 25^{\circ}C$ to MAX		±0.004			±0.001		%FSR/°C

NOTES: 1. Gain error is measured using the internal feedback resistor. Nominal full-scale range (FSR) = V_{ref} - 1 LSB.
2. OUT1 load = 100 Ω, C_{ext} = 13 pF, WR at 0 V, CS at 0 V, DB0 - DB7 at 0 V to V_{DD} or V_{DD} to 0 V.

operating sequence





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PRINCIPLES OF OPERATION

voltage-mode operation

It is possible to operate the current-multiplying DAC in these devices in a voltage mode. In the voltage mode, a fixed voltage is placed on the current output terminal. The analog output voltage is then available at the reference voltage terminal. Figure 1 is an example of a current-multiplying DAC, which is operated in voltage mode.

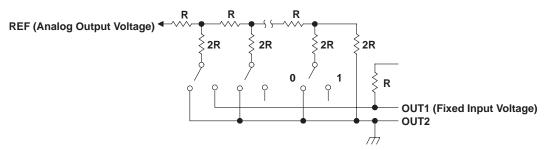


Figure 1. Voltage Mode Operation

The relationship between the fixed-input voltage and the analog-output voltage is given by the following equation:

$$V_{O} = V_{I} (D/256)$$

where

 V_{O} = analog output voltage

 V_{I} = fixed input voltage

D = digital input code converted to decimal

In voltage-mode operation, these devices meet the following specification:

PARAMETER		TEST CON	DITIONS		MIN	MAX	UNIT
Linearity error at REF	V _{DD} = 5 V,	OUT1 = 2.5 V,	OUT2 at GND,	$T_A = 25^{\circ}C$		1	LSB



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PRINCIPLES OF OPERATION

The TLC7524C, TLC7524E, and TLC7524I are 8-bit multiplying DACs consisting of an inverted R-2R ladder, analog switches, and data input latches. Binary-weighted currents are switched between the OUT1 and OUT2 bus lines, thus maintaining a constant current in each ladder leg independent of the switch state. The high-order bits are decoded. These decoded bits, through a modification in the R-2R ladder, control three equally-weighted current sources. Most applications only require the addition of an external operational amplifier and a voltage reference.

The equivalent circuit for all digital inputs low is seen in Figure 2. With all digital inputs low, the entire reference current, I_{ref} , is switched to OUT2. The current source I/256 represents the constant current flowing through the termination resistor of the R-2R ladder, while the current source I_{lkg} represents leakage currents to the substrate. The capacitances appearing at OUT1 and OUT2 are dependent upon the digital input code. With all digital inputs high, the off-state switch capacitance (30 pF maximum) appears at OUT2 and the on-state switch capacitance (120 pF maximum) appears at OUT1. With all digital inputs low, the situation is reversed as shown in Figure 2. Analysis of the circuit for all digital inputs high is similar to Figure 2; however, in this case, I_{ref} would be switched to OUT1.

The DAC on these devices interfaces to a microprocessor through the data bus and the \overline{CS} and \overline{WR} control signals. When \overline{CS} and \overline{WR} are both low, analog output on these devices responds to the data activity on the DB0–DB7 data bus inputs. In this mode, the input latches are transparent and input data directly affects the analog output. When either the \overline{CS} signal or \overline{WR} signal goes high, the data on the DB0–DB7 inputs are latched until the \overline{CS} and \overline{WR} signals go low again. When \overline{CS} is high, the data inputs are disabled regardless of the state of the \overline{WR} signal.

These devices are capable of performing 2-quadrant or full 4-quadrant multiplication. Circuit configurations for 2-quadrant or 4-quadrant multiplication are shown in Figure 3 and Figure 4. Table 1 and Table 2 summarize input coding for unipolar and bipolar operation respectively.

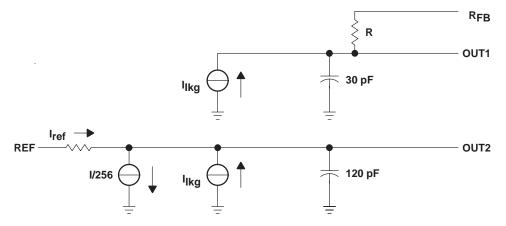
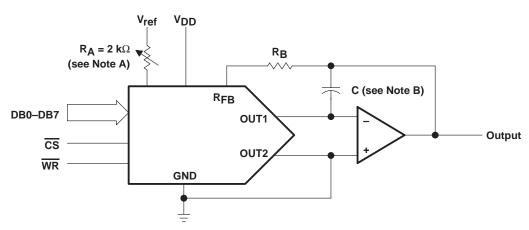


Figure 2. TLC7524 Equivalent Circuit With All Digital Inputs Low



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PRINCIPLES OF OPERATION



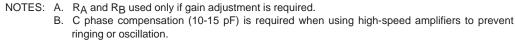
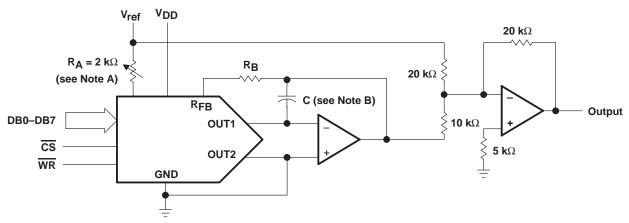


Figure 3. Unipolar Operation (2-Quadrant Multiplication)



NOTES: A. $\ensuremath{\mathsf{R}}_A$ and $\ensuremath{\mathsf{R}}_B$ used only if gain adjustment is required.

B. C phase compensation (10-15 pF) is required when using high-speed amplifiers to prevent ringing or oscillation.

Figure 4. Bipolar Operation (4-Quadrant Operation)

Table	1	Unin	olar	Binary	Code
able		Unip	Ulai	Dillary	COUE

	bolar Billary boac
DIGITAL INPUT (see Note 3)	ANALOG OUTPUT
MSB LSB	
11111111	-V _{ref} (255/256)
1000001	-V _{ref} (129/256)
1000000	$-V_{ref}$ (128/256) = $-V_{ref}/2$
01111111	-V _{ref} (127/256)
0000001	-V _{ref} (1/256)
00000000	0

NOTE 3: LSB = 1/256 (V_{ref})

Table 2. Bipolar (Offset Binary) Code

i	
DIGITAL INPUT (see Note 4)	ANALOG OUTPUT
MSB LSB	1
11111111	V _{ref} (127/128)
1000001	V _{ref} (1/128)
10000000	0
01111111	-V _{ref} (1/128)
0000001	-V _{ref} (127/128)
00000000	-V _{ref}

NOTE 4: LSB = 1/128 (V_{ref})



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PRINCIPLES OF OPERATION

microprocessor interfaces

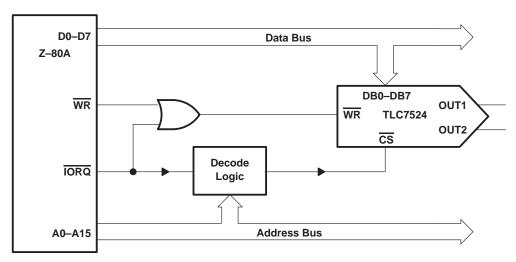


Figure 5. TLC7524 – Z-80A Interface

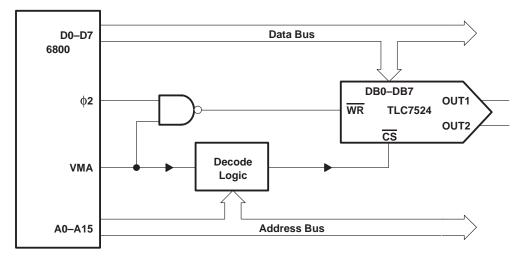
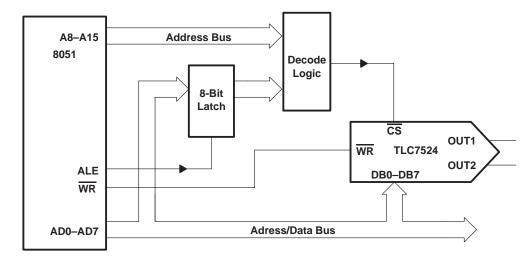


Figure 6. TLC7524 – 6800 Interface



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PRINCIPLES OF OPERATION



microprocessor interfaces (continued)

Figure 7. TLC7524 – 8051 Interface



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